



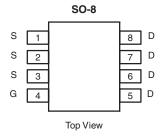
# N-Channel Reduced $Q_g$ , Fast Switching MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}$ ( $\Omega$ )	I <sub>D</sub> (A)			
30	$0.012$ at $V_{GS} = 10 \text{ V}$	± 11			
30	0.020 at $V_{GS} = 4.5 \text{ V}$	± 9			

# **FEATURES**

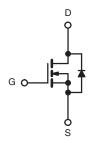
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFETs
- High-Efficiency PWM Optimized
- Compliant to RoHS Directive 2002/95/EC





Ordering Information: Si4890DY-T1-E3 (Lead (Pb)-free)

Si4890DY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b>	T <sub>A</sub> = 25 °C, unles	ss otherwise no	ted		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	30		
Gate-Source Voltage		V <sub>GS</sub>	± 25	V	
Continuous Drain Current (T <sub>.I</sub> = 150 °C) <sup>a, b</sup>	T <sub>A</sub> = 25 °C	I-	± 11		
Continuous Drain Current (1 <sub>J</sub> = 150 °C)	T <sub>A</sub> = 70 °C	I <sub>D</sub>	± 9	_	
Pulsed Drain Current (10 µs Pulse Width)		I <sub>DM</sub>	± 50	A	
Continuous Source Current (Diode Conduction) <sup>a, b</sup>		I <sub>S</sub>	2.3		
Mariana Barra Britania h	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.5	w	
Maximum Power Dissipation <sup>a, b</sup>	T <sub>A</sub> = 70 °C	' D	1.6	l vv	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Marrian In Ambient (MOCFFT)	t ≤ 10 s	$R_{thJA}$		50	°C/W	
Maximum Junction-to-Ambient (MOSFET) <sup>a</sup>	Steady State	' 'thJA	70		C/VV	

### Notes

a. Surface Mounted on FR4 board.

 $b.\ t \leq 10\ s.$ 

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MOSFET SPECIFICATIONS T <sub>J</sub> = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.8			V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	1	V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V		1			
	IDSS	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			5	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	40			Α	
	D	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 11 A		0.0098	0.012	0	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 9 A		0.0164	0.020	Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 11 A		21		S	
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>S</sub> = 2.3 A, V <sub>GS</sub> = 0 V		0.71	1.1	V	
Dynamic <sup>b</sup>							
Total Gate Charge	$Q_g$			14.2	20		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 5.0 \text{ V}, I_D = 11 \text{ A}$		3.3		nC	
Gate-Drain Charge	$Q_{gd}$			6.6			
Turn-On Delay Time	t <sub>d(on)</sub>			13	20		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 15 $\Omega$		8.5	15		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ 1 A, $V_{GEN}$ = 10 V, $R_g$ = 6 $\Omega$		35	53	ns	
Fall Time	t <sub>f</sub>			17	26		
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	$I_F = 2.3 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$		35	70		

## Notes:

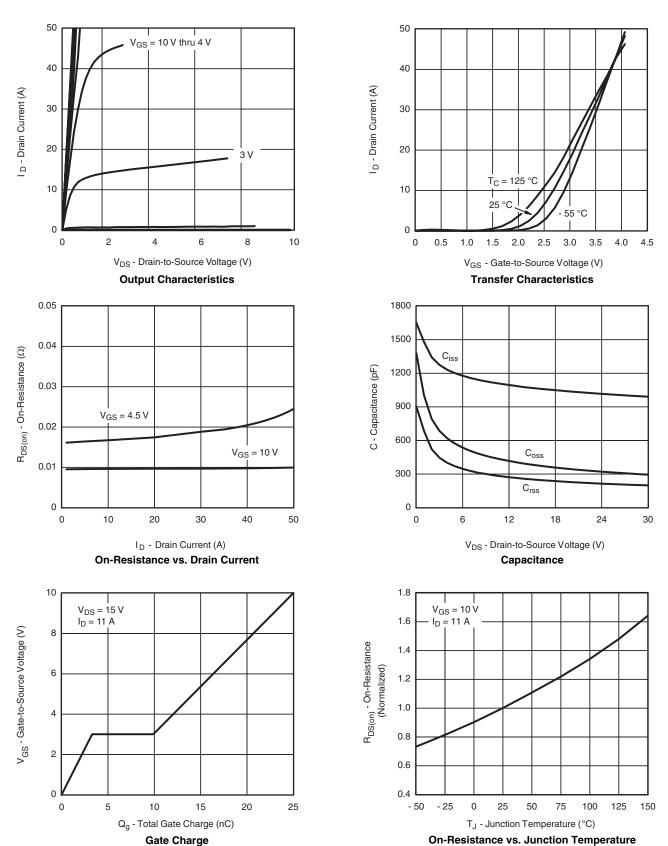
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

b. Guaranteed by design, not subject to production testing.



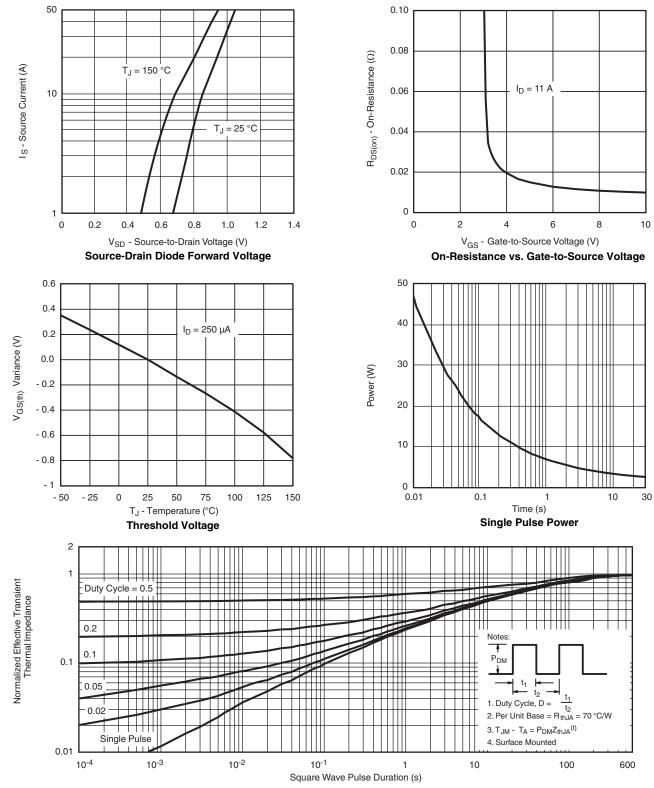
# TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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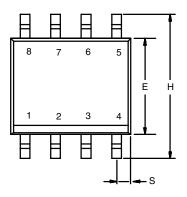


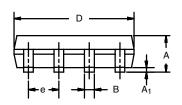
Normalized Thermal Transient Impedance, Junction-to-Ambient

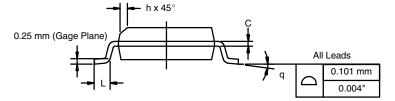
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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIMETERS INCHES			HES	
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050	BSC	
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I. 11-Sep-06					

DWG: 5498

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# APPLICATION NOTE



# **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)

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